Lumina AT1 Defect Scanner

FOUR DETECTION CHANNELS:

- Polarization (Stains, Film Non-uniformity)
- Slope (Scratches, Surface Topography)
- Reflectivity (Internal Stress, Striations)
- Dark Field (Particles, Inclusions)

EFFECTIVE

Full-surface scan with sub-nanometer sensitivity

COMPATIBLE

Scan any shape as large as 300 X 300mm

EFFICIENT

Scan a 150 x 150mm sample under 4 minutes

RESILIENT

Capable of scanning fragile and thin glass

- Enables full surface scan and imaging of sub-nanometer film coatings, nanometer size particles, scratches, pits, bumps, stress points and other defects.

- Scan and displays a 150mm wafer under 4 minutes.

- Capable on transparent, silicon, compound semiconductor and metal substrates.

- Accommodates non-circular and fragile substrates up to 300 x 300mm.

- Able to separate top/bottom features on transparent substrates with a single scan.

- Can scribe locations of defects for further analysis.

Using data from any combination of the multiple detectors the AT1 software generates the defect map and report:

- Map and location
- Color coded defects
- Size of defects
- Quantity of defects
- Image of defects
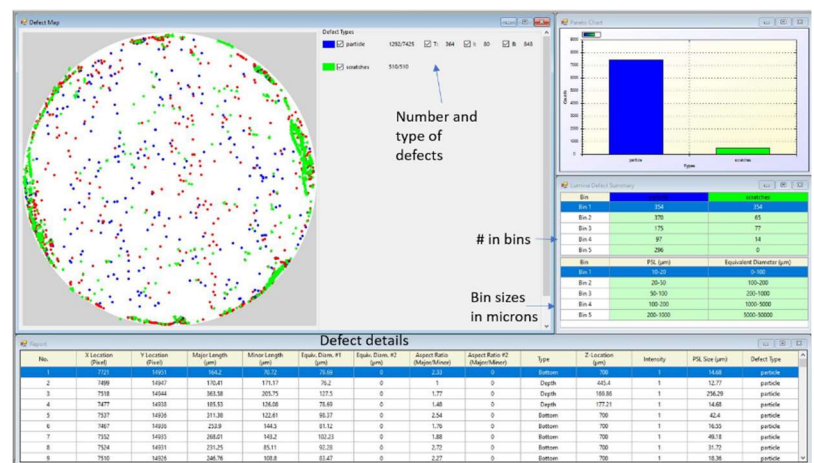
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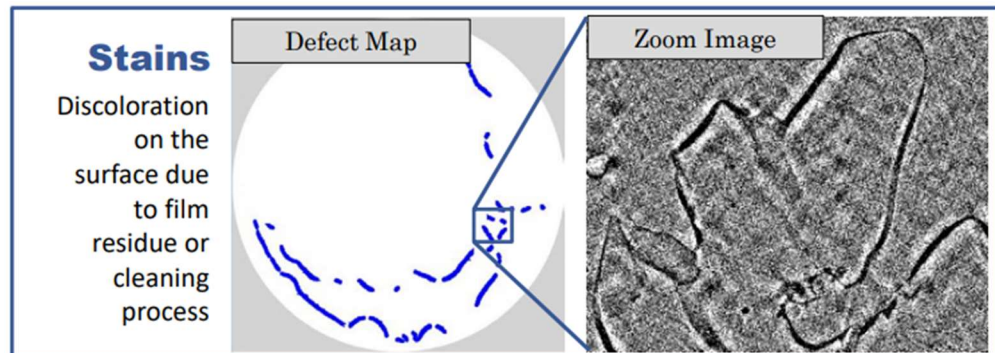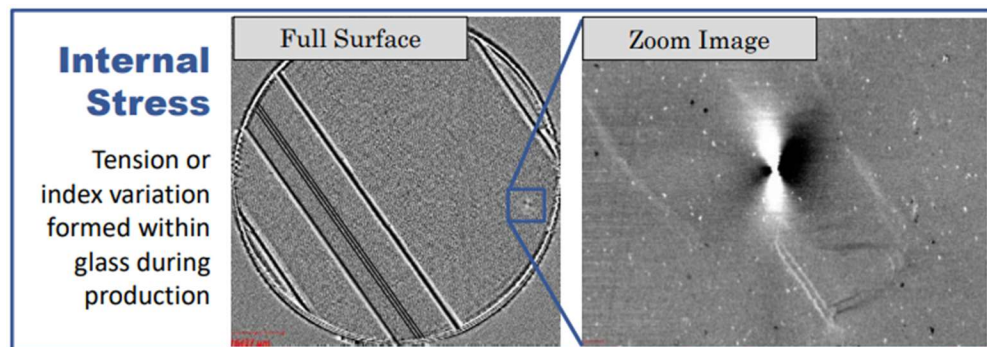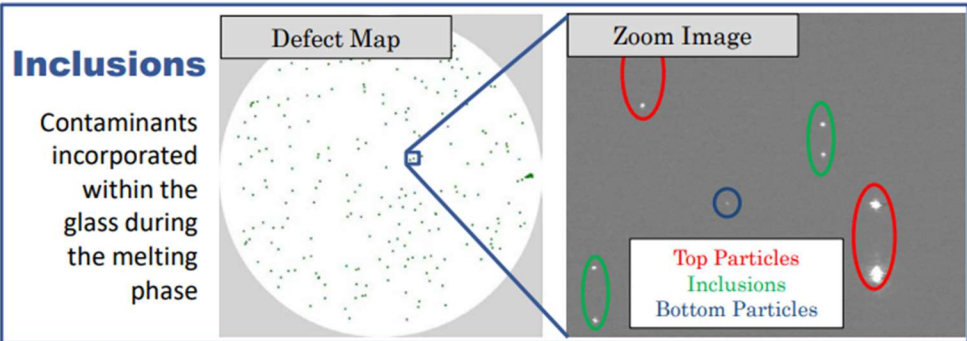# Defects on Transparent Substrates

- Both exterior and interior
- Film residue and water marks from cleaning or other processes
- Internal stress or refractive index variation
- Work with thin glass without backside interference

CLEAN AND GENTLE HANDLING

- No need for vacuum
- Edge contact
- Scan any shape
- Work with fragile samples
- High immunity to vibration

EFFICIENT

- Detect defects on top surface, bottom surface, and inclusions with one scan
- Report depth of internal defects

Inclusions

Contaminants incorporated within the glass during the melting phase

Defect Map — Zoom Image

Top Particles
Inclusions
Bottom Particles

Internal Stress

Tension or index variation formed within glass during production

Full Surface — Zoom Image

Stains

Discoloration on the surface due to film residue or cleaning process

Defect Map — Zoom Image

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Sub-nanometer sensitivity in full surface scanning of thin-film contamination

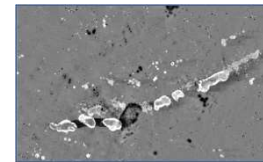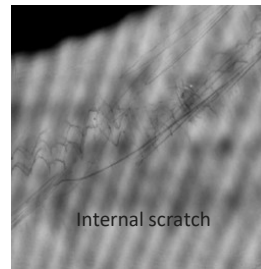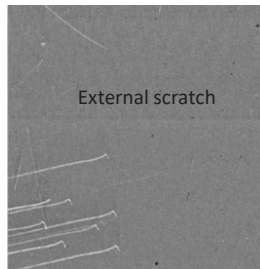Ellipsometry sensitivity at full surface scanning speed

VERSATILE

- All defect types
- Thin and thick substrates
- Transparent and opaque substrates
- Dielectric coated
- Metallic coated
- Bonded wafers
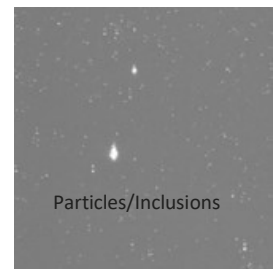- Developmennt and inline production

Coating Thickness

7 nm
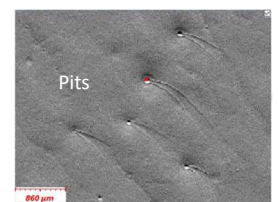6 nm
5 nm
4 nm
3 nm
2 nm
1 nm
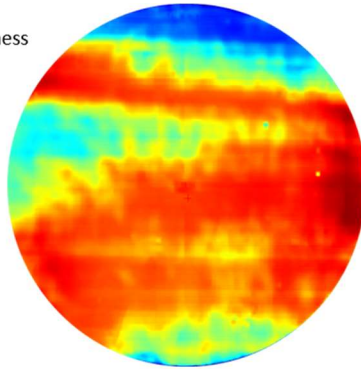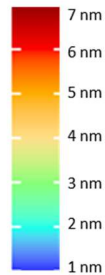
Monolayer stains or thin-film non-uniformity

- Stains
- Water marks
- Voids
- Bubbles
- Fingerprints

External scratch

Internal scratch

Dark: Top surface stain
Bright: Bottom surface stain

Particles/Inclusions

Defect examples on glass

Pits/Depressions

Ridges

Pits

2236 µm

Bumps

1935 µm

Pits

860 µm
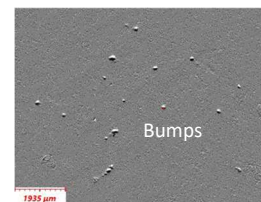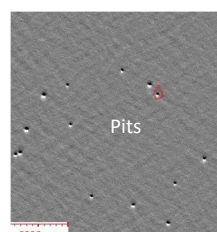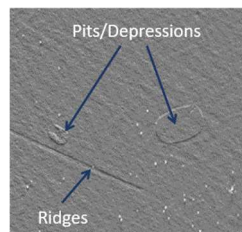
Defect examples on Si wafers
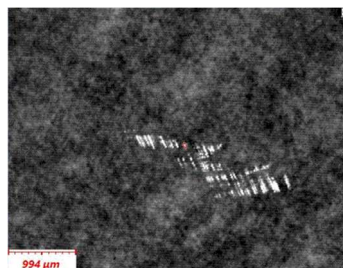
Scratches from oxide CMP

994 µm

Scratches from Si wafer backside thinning

994 µm

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Crystal Defects on Compound Semiconductor

CRYSTAL DEFECTS

Detect and classify many types of crystal defects on compound semiconductor substrates and epitaxial growth layer
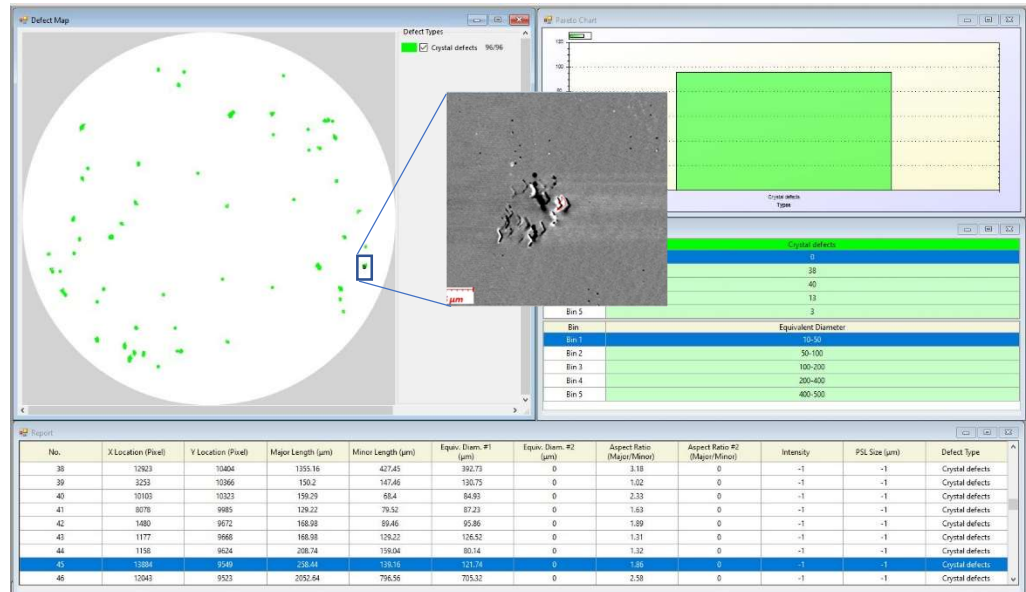

NEED MORE AUTOMATION?

AT1-Auto - Fully automated production systems for substrate size 200 x 200mm or smaller with factory automation capability

System Specifications

Scan time	150mm wafer under 4 minutes
Scan area	300 x 300mm
Sensitivity	Film defects < 0.5nm
	Particles, 100nm PSL on Si
	Particles, 150nm PSL on glass
Scribe	Diamond scribe
Temp	18 – 30 ^{0}C
Voltage	120 / 230VAC
Current	6A / 4A
Weight	370Kg (815lbs)
Dimension	880 x 743 x 2005mm
	(34.6 x 29.2 x 79 inches)
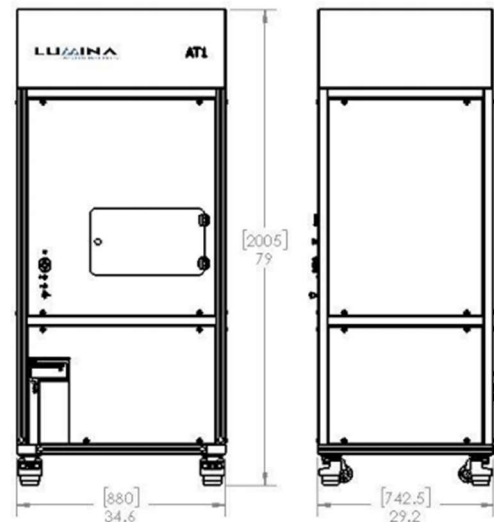
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2109 O'Toole Ave. Suite P
San Jose, CA 95131
Phone: +1.408.649.3456
Email: info@lumina-inst.com
www.lumina-inst.com